COMPONENTS MARKED 'DNP' SHOULDN'T BE POPULATED.

ASSEMBLY VARIANTS: 001

PCB VIEWED FROM TOP SIDE

BOARD #: PRR2144D  REV: A  SUN REV: Not In VersionControl
TID #: N/A

PLOT NAME: Top Assembly Drawing  GENERATED: 4/9/2018  10:47:30 AM  TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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<th>BOARD #</th>
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